8 T V_{CC+}

7 DY

5 🕇 RA

6 RTC

D OR P PACKAGE TOP VIEW

 V_{CC}

DA [

RY **∏**

GND [

3

SLLS017C - JULY 1986 - REVISED MAY 1995

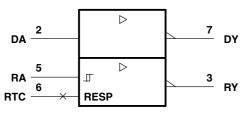
- Meets or Exceeds the Requirements of ANSI EIA/TIA-232-E and ITU Recommendation V.28
- 10-mA Current Limited Output
- Wide Range of Supply Voltage
 V_{CC} = 4.5 V to 15 V
- Low Power . . . 130 mW
- Built-In 5-V Regulator
- Response Control Provides: Input Threshold Shifting Input Noise Filtering
- Power-Off Output Resistance . . . 300 Ω Typ
- Driver Input TTL Compatible

description

The SN75155 monolithic line driver and receiver is designed to satisfy the requirements of the standard interface between data terminal equipment and data communication equipment as defined by ANSI EIA/TIA-232-E. A response control input is provided for the receiver. A resistor or a resistor and a bias voltage can be connected between the response control input and ground to provide noise filtering. The driver used is similar to the SN75188. The receiver used is similar to the SN75189A.

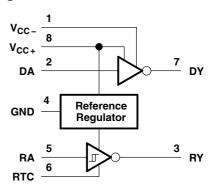
The SN75155 is characterized for operation from 0°C to 70°C.

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12

logic diagram

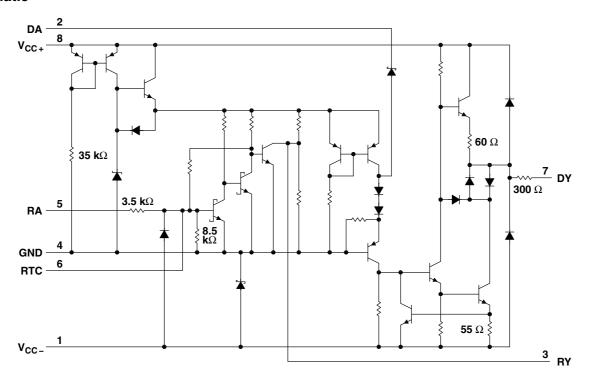




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC+} (see Note 1)	15 V
Supply voltage, V _{CC} (see Note 1)	
Input voltage range, V _I : Driver	–15 V to 15 V
Receiver	–30 V to 30 V
Output voltage range (driver), V _O	–15 V to 15 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{sta}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
D	725 mW	5.8 mW/°C	464 mW		
Р	1000 mW	8.0 mW/°C	640 mW		



recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC+}	4.5	12	15	V
Supply voltage, V _{CC} _	-4.5	-12	-15	V
Output voltage, driver, V _{O(D)}			±15	V
Input voltage, receiver, V _{I(R)}	-25		25	V
High-level input voltage, driver, V _{IH}	2			٧
Low-level input voltage, driver, V _{IL}			8.0	V
Response control current			±5.5	mA
Output current, receiver, I _{O(R)}			24	mA
Operating free-air temperature, T _A	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

total device

	PARAMETER		TEST CONDITIONS	S	MIN	TYP [†]	MAX	UNIT
		$V_{CC+} = 5 V$,	V _{CC} = -5 V	$V_{I(D)} = 2 V,$		6.3	8.1	
I _{CCH+}	High-level supply current	$V_{CC+} = 9 V$,	$V_{CC} = -9 \text{ V}$	$V_{I(R)} = 2.3 \text{ V},$		9.1	11.9	mA
		$V_{CC+} = 12 \text{ V},$	V _{CC} = -12 V	Output open		10.4	14	
		$V_{CC+} = 5 \text{ V},$	V _{CC} = -5 V	$V_{I(D)} = 0.8 \text{ V},$		2.5	3.4	
I _{CCL+}	Low-level supply current	$V_{CC+} = 9 V$,	$V_{CC} = -9 \text{ V}$	$V_{I(R)} = 0.6 \text{ V},$		3.7	5.1	mA
		$V_{CC+} = 12V$,	$V_{CC-} = -12 \text{ V}$	Output open		4.1	5.6	
	0	$V_{CC+} = 5 V$,	V _{CC} – = 0	$V_{I(R)} = 2.3 \text{ V},$		4.8	6.4	
I _{CC+}	Supply current	$V_{CC+} = 9 V$,	V _{CC} _ = 0	$V_{I(D)} = 0$		6.7	9.1	mA
		$V_{CC+} = 5 V$,	$V_{CC} = -5 \text{ V}$	$V_{I(D)} = 2 V,$		-2.4	-3.1	
I _{CCH} -	High-level supply current	$V_{CC+} = 9 V$,	$V_{CC} = -9 \text{ V}$	$V_{I(R)} = 2.3 \text{ V}$		-3.9	-4.9	mA
		$V_{CC+} = 12 \text{ V},$	V _{CC} = -12 V	Output open		-4.8	-6.1	
		$V_{CC+} = 5 \text{ V},$	V _{CC} = -5 V	$V_{I(D)} = 0.8 \text{ V},$		-0.2	-0.35	
I _{CCL} _	Low-level supply current	$V_{CC+} = 9 V$,	V _{CC} = -9 V	$V_{I(R)} = 0.6 \text{ V},$		-0.25	-0.4	mA
		$V_{CC+} = 12 \text{ V},$	V _{CC} = -12 V	Output open		-0.27	-0.45	

[†] All typical values are at $T_A = 25$ °C.

SLLS017C - JULY 1986 - REVISED MAY 1995

electrical characteristics over recommended operating free-air temperature range, V_{CC+} = 12 V, $V_{CC-} = -12 \text{ V (unless otherwise noted)}$

driver section

	PARAMETER		TES	T CONDITIONS		MIN	TYP†	MAX	UNIT
				$V_{CC+} = 5 V$,	$V_{CC} = -5 \text{ V}$	3.2	3.7		
V_{OH}	High-level output voltage	$V_{IL} = 0.8 V,$	$R_L = 3 \text{ k}\Omega$	$V_{CC+} = 9 V$,	$V_{CC-} = -9 V$	6.5	7.2		٧
				$V_{CC+} = 12 V$,	$V_{CC-} = -12 \text{ V}$	8.9	9.8		
				$V_{CC+} = 5 V$,	$V_{CC} = -5 \text{ V}$		-3.6	-3.2	
V _{OL}	Low-level output voltage (see Note 2)	V _{IH} = 2 V,	$R_L = 3 \text{ k}\Omega$	$V_{CC+} = 9 V$,	$V_{CC} = -9 \text{ V}$		-7.1	-6.4	V
	(000 11010 2)			$V_{CC+} = 12 V$,	$V_{CC-} = -12 \text{ V}$		-9.7	-8.8	
I _{IH}	High-level input current	$V_I = 7 V$						5	μΑ
I _{IL}	Low-level input current	$V_I = 0$					-0.73	-1.2	mA
I _{OS(H)}	High-level short-circuit output current	V _I = 0.8 V,	V _O = 0			-7	-12	-14.5	mA
I _{OS(L)}	Low-level short-circuit output current	V _I = 2 V,	V _O = 0			6.5	11.5	15	mA
r _O	Output resistance with power off	$V_O = -2 \text{ V to}$	o 2 V				300		Ω

receiver section (see Figure 1)

	PARAMETER		TEST CONDITION	ONS	MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going input threshhold voltage				1.2	1.9	2.3	V
V _{IT} _	Negative-going input threshhold voltage				0.6	0.95	1.2	٧
V _{hys}	Hystresis voltage (V _{IT+} – V _{IT-})				0.6			V
		V _I = 0.6 V,	$V_{CC+} = 5 V$,	$V_{CC-} = -5 \text{ V}$	3.7	4.1	4.5	
,	High-level output voltage	$I_{OH} = 10 \mu A$	$V_{CC+} = 12 V$,	$V_{CC-} = -12 \text{ V}$	4.4	4.7	5.2	.,
V _{O(H)}		$V_{I} = 0.6 V,$ $I_{OH} = 0.4 \text{ mA}$	$V_{CC+} = 5 V$,	$V_{CC} = -5 \text{ V}$	3.1	3.4	3.8	V
			$V_{CC+} = 12 \text{ V},$	$V_{CC-} = -12 \text{ V}$	3.6	4	4.5	
$V_{O(L)}$	Low-level output voltage	$V_I = 2.3 V$,	$I_{OL} = 24 \text{ mA}$			0.2	0.3	V
	Little Land Count comment	V _I = 2 5 V			3.6	6.7	10	mA
I _{IH}	High-level input current	V _I = 3 V			0.43	0.67	1	mA
	Laure laure l'innered accommand	$V_{I} = -25 \text{ V}$			-3.6	-6.7	-10	mA
I _{IL}	I _{IL} Low-level input current			-0.43	-0.67	-1	mA	
Ios	Short-circuit output current	$V_1 = 0.6 V$				-2.8	-3.7	mA

[†] All typical values are at $T_A = 25$ °C.

NOTE 2: The algebraic limit system, in which the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic voltage levels only (e.g., if –8.8 V is the maximum, the typical value is a more negative value).



switching characteristics over recommended operating free-air temperature range, V_{CC+} = 5 V, V_{CC-} = -5 V, C_L = 50 pF (unless otherwise noted)

driver section (see Figure 2)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high level output	B alo		250	480	
t _{PHL}	Propagation delay time, high- to low level output	$R_L = 3 \text{ k}\Omega$		80	150	ns
	Outrot diag time	$R_L = 3 \text{ k}\Omega$		67	180	ns
ι _r	Output rise time	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega, \qquad C_L = 2500 \text{ pF}$		2.4	3	μs
	Output fall time	$R_L = 3 \text{ k}\Omega$		48	160	ns
Ч	Output fair time	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega, \qquad C_L = 2500 \text{ pF}$		1.9	3	μs

receiver section (see Figure 3)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high level output	B 400 C		175	245	
t _{PHL}	Propagation delay time, high- to low level output	$R_L = 400 \Omega$		37	100	ns
t _r	Output rise time	$R_L = 400 \Omega$		255	360	ns
t _f	Output fall time	$R_L = 400 \Omega$		23	50	ns

[†] All typical values are at $T_A = 25$ °C.

PARAMETER MEASUREMENT INFORMATION

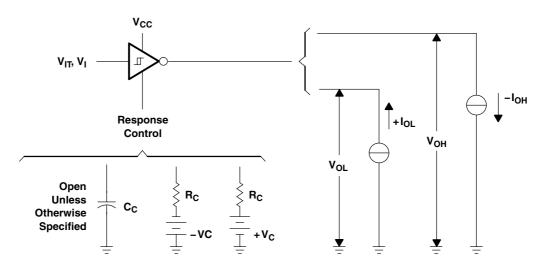
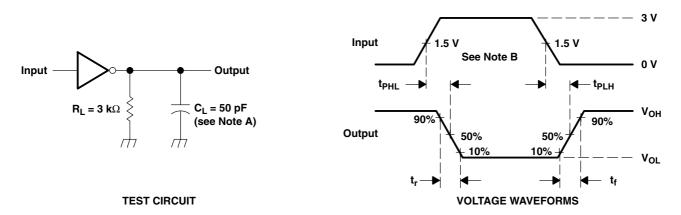


Figure 1. Receiver Section Test Circuit (V_{IT+} , V_{IT-} , V_{OH} , V_{OL})

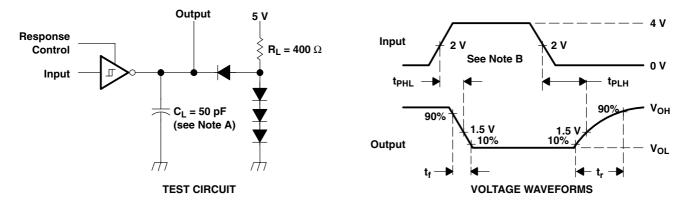
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The input waveform is supplied by a generator with the following characteristics: $Z_O = 50 \ \Omega$, $t_W = 1 \ \mu s$, $t_f \le 10 \ ns$.

Figure 2. Driver Section Switching Test Circuit and Voltage Waveforms

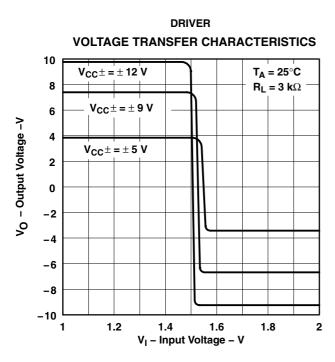


NOTES: A. C_L includes probe and jig capacitance.

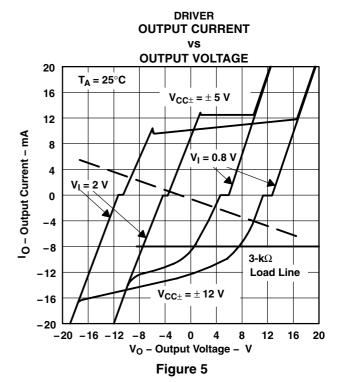
B. The input waveform is supplied by a generator with the following characteristics: $Z_Q = 50 \Omega$, $t_W = 1 \mu s$, $t_f \le 10 ns$, $t_f \le 10 ns$.

Figure 3. Receiver Section Switching Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS







DRIVER
SHORT-CIRCUIT OUTPUT CURRENT

DRIVER
SLEW RATE
vs

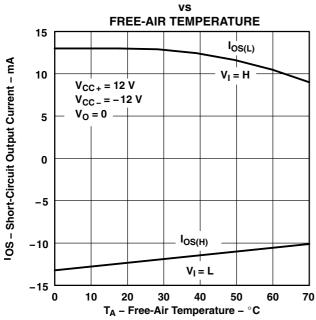


Figure 6

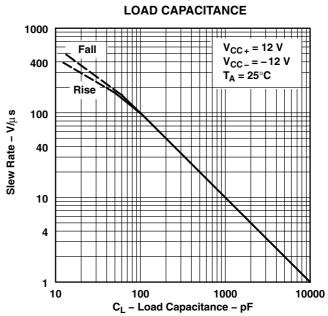
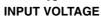


Figure 7

TYPICAL CHARACTERISTICS

RECEIVER OUTPUT VOLTAGE



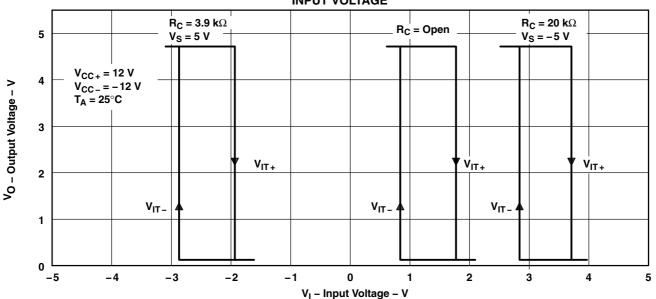


Figure 8

RECEIVER OUTPUT VOLTAGE

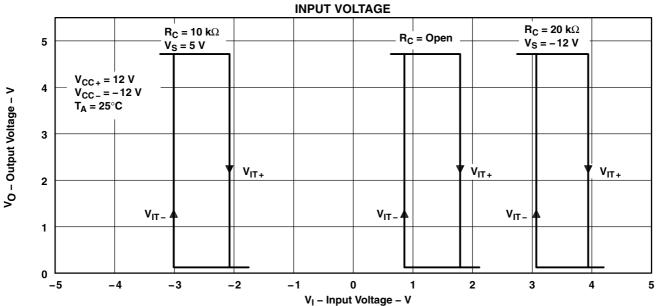
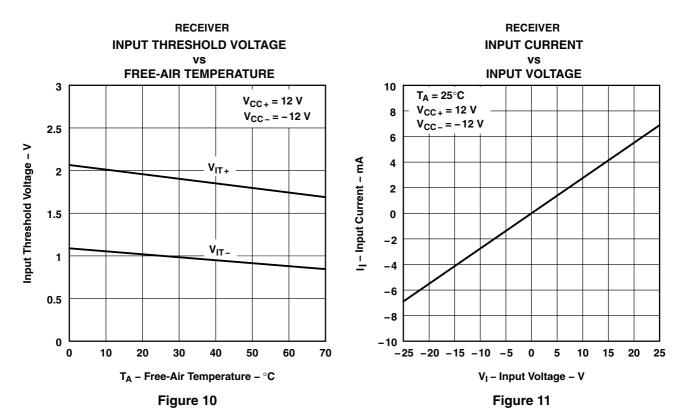
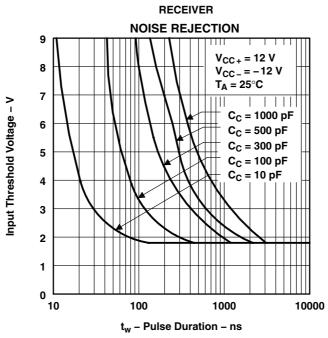


Figure 9



TYPICAL CHARACTERISTICS





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Figure 12

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN75155D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	75155	
SN75155DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155DRE4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155P	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75155P	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: Til defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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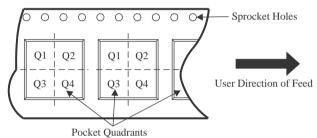
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75155DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN75155DR	SOIC	D	8	2500	340.5	336.1	25.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75155P	Р	PDIP	8	50	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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